

Electronic Patent Application Fee Transmittal

| Application Number: | 10517764 | | | |
|---|---|----------|--------|----------------------|
| Filing Date: | 23-Dec-2004 | | | |
| Title of Invention: | ANISOTROPIC DRY ETCHING OF CU-CONTAINING LAYERS | | | |
| First Named Inventor/Applicant Name: | Lee Chen | | | |
| Filer: | Marvin Jay Spivak/Slobodanka Alic | | | |
| Attorney Docket Number: | 261137US6YAPCT | | | |
| Filed as Large Entity | | | | |
| U.S. National Stage under 35 USC 371 Filing Fees | | | | |
| Description | Fee Code | Quantity | Amount | Sub-Total in USD(\$) |
| Basic Filing: | | | | |
| Pages: | | | | |
| Claims: | | | | |
| Miscellaneous-Filing: | | | | |
| Petition: | | | | |
| Patent-Appeals-and-Interference: | | | | |
| Post-Allowance-and-Post-Issuance: | | | | |
| Utility Appl issue fee | 1501 | 1 | 1400 | 1400 |
| Publ. Fee- early, voluntary, or normal | 1504 | 1 | 300 | 300 |

| Description | Fee Code | Quantity | Amount | Sub-Total in USD(\$) |
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| Extension-of-Time: | | | | |
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| Total in USD (\$) | | | | 1700 |